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Chen et al.

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(54) **HEAT DISSIPATING MODULE OF MEMORY**

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(**) Term: **14 Years**

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(51) **LOC (9) Cl.** **13-03**

(52) **U.S. Cl.**
USPC **D13/179**

(58) **Field of Classification Search**
USPC D13/179; 165/80.3, 104.26, 104.33,
165/122, 151, 185; 257/706, 707, 718-722;
361/679.54, 695, 697, 700, 702, 704, 707,
361/709, 710, 711, 715, 719
See application file for complete search history.

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(57) **CLAIM**

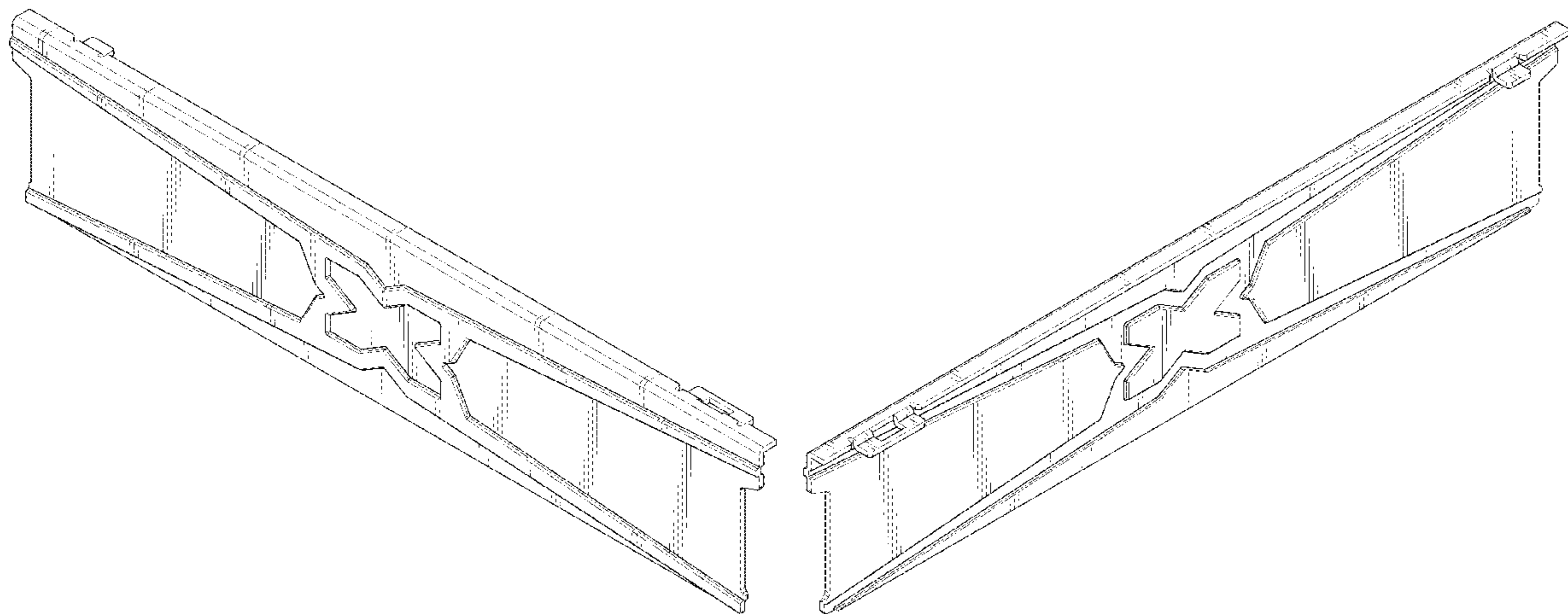
The ornamental design for a heat dissipating module of memory, as shown and described.

DESCRIPTION

FIG. 1 is a perspective view of a heat dissipating module of memory showing our new design;
FIG. 2 is a front view thereof;
FIG. 3 is a rear view thereof;
FIG. 4 is a left side view thereof;
FIG. 5 is a right side view thereof;
FIG. 6 is a top view thereof;
FIG. 7 is a bottom view thereof; and
FIG. 8 is the other perspective view showing the heat dissipating module of memory; and,
FIG. 9 is a perspective view of the heat dissipating module of memory for reference.

The broken lines shown represent unclaimed subject matter and form no part of the claimed design.

1 Claim, 7 Drawing Sheets



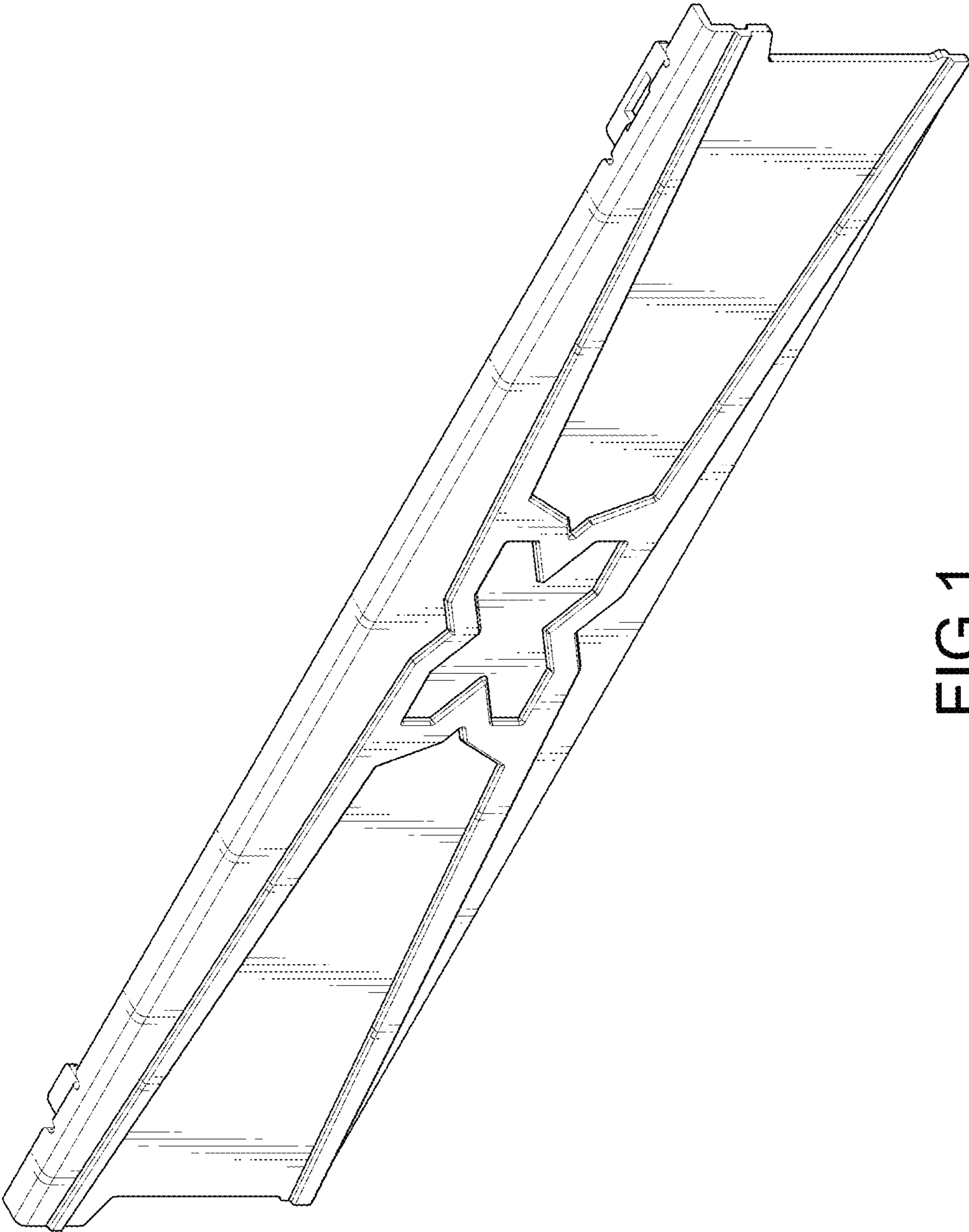


FIG.1

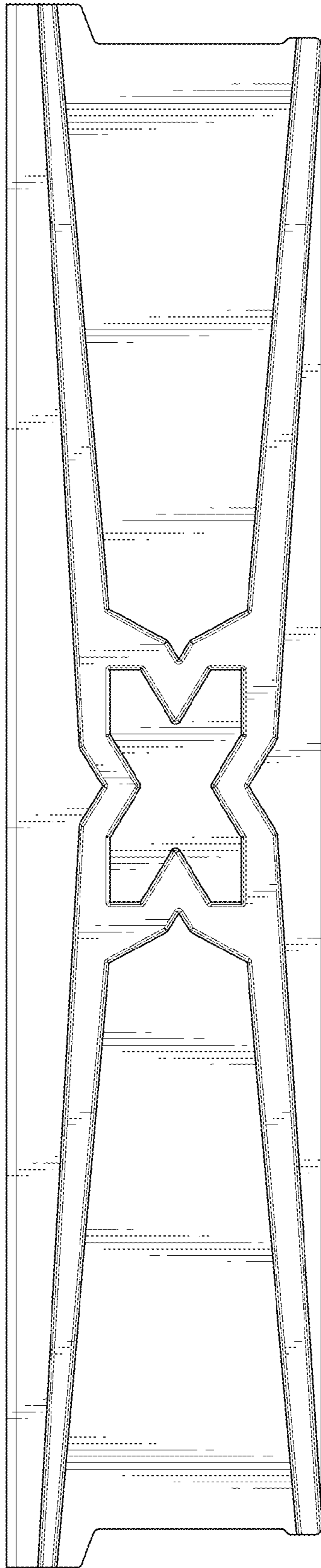


FIG.2

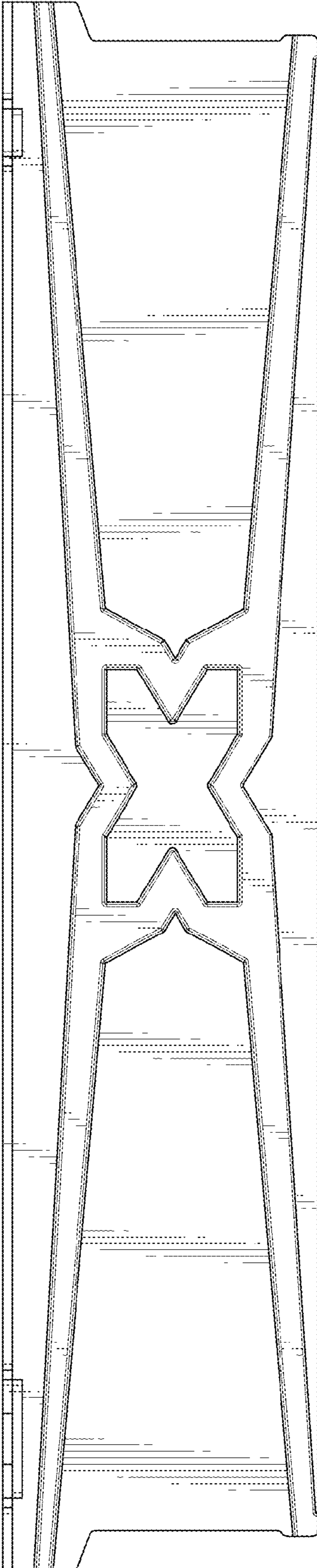


FIG.3

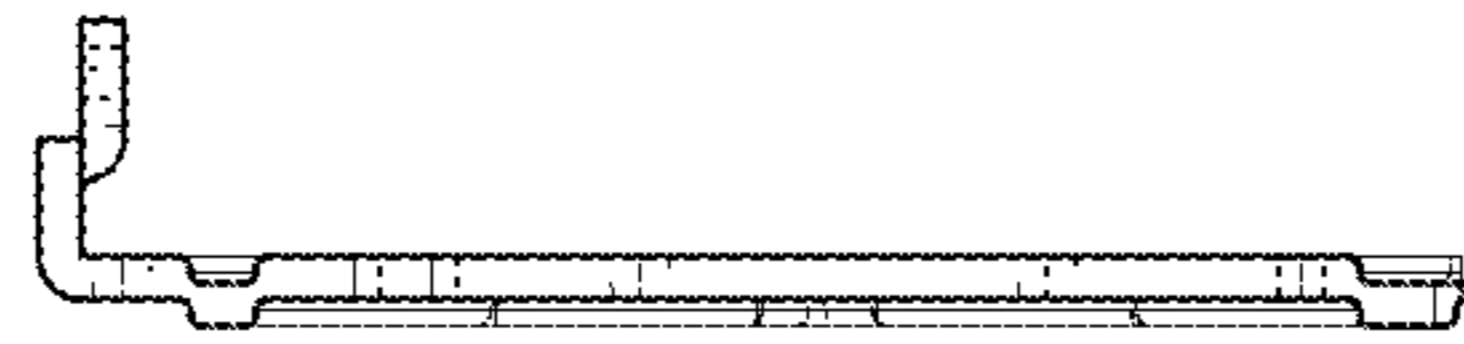


FIG.5

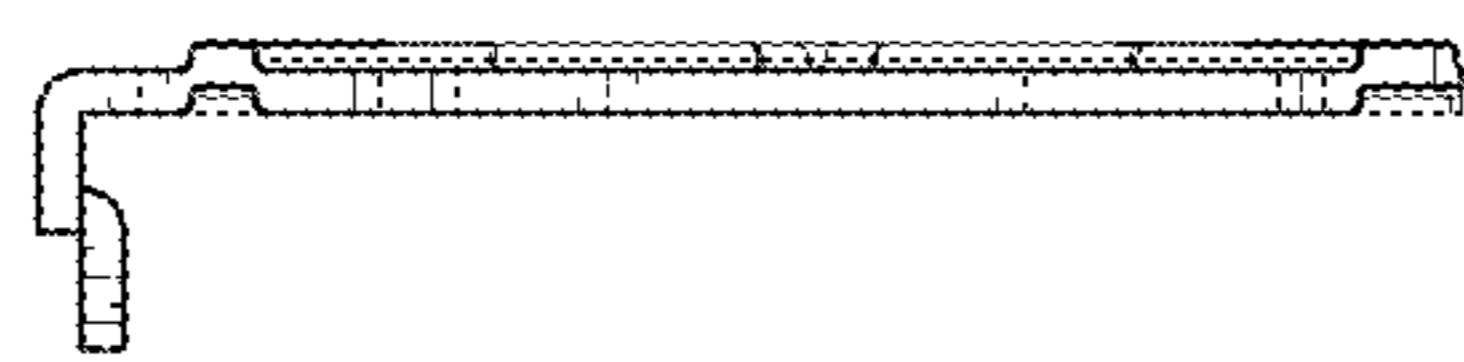


FIG.4

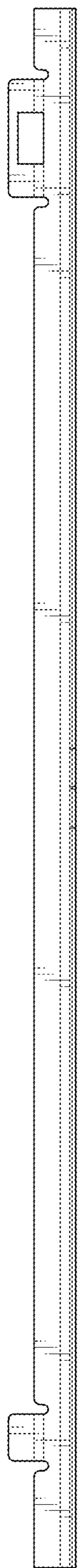


FIG. 6

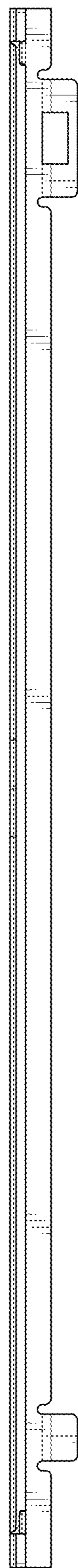


FIG. 7

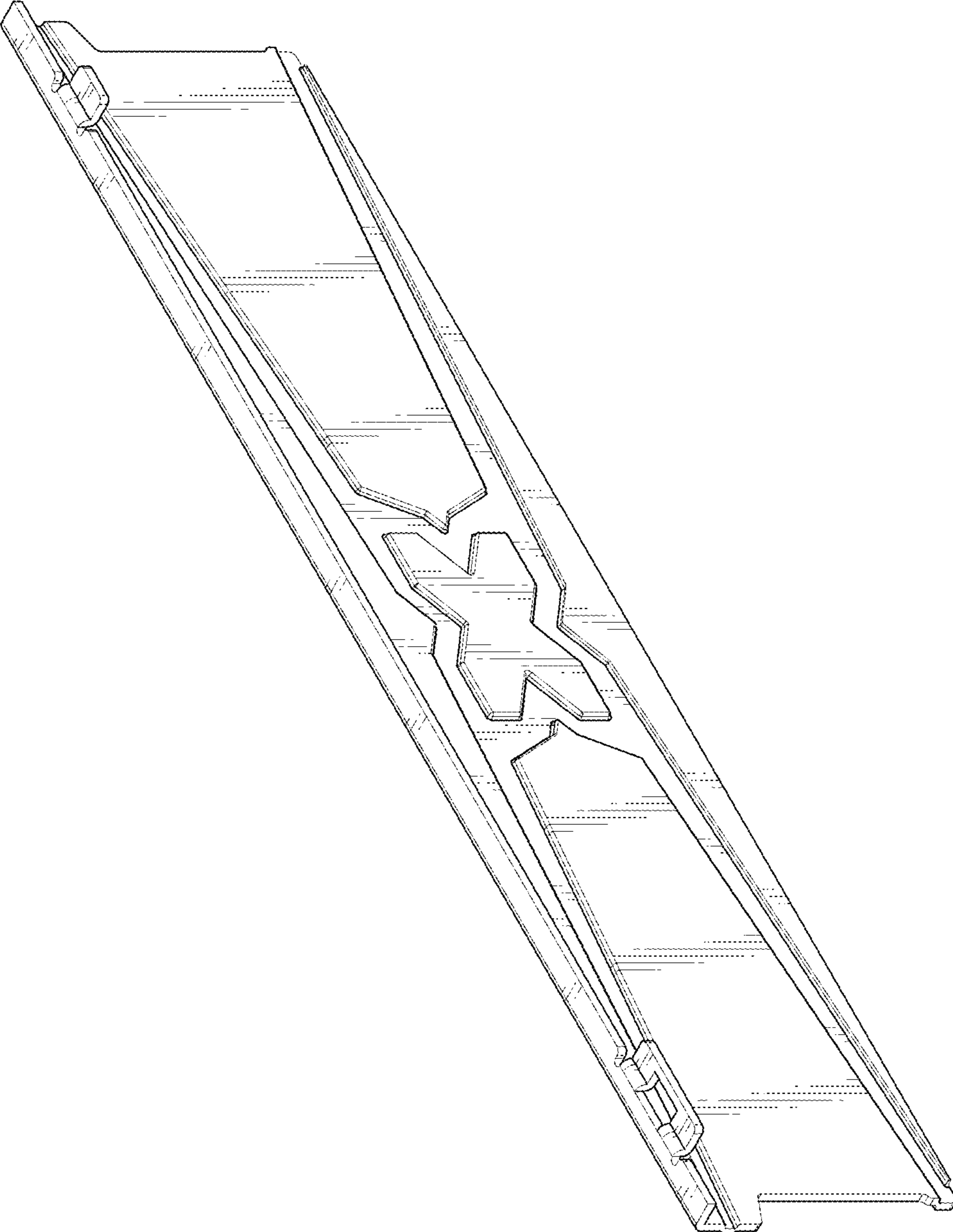


FIG. 8

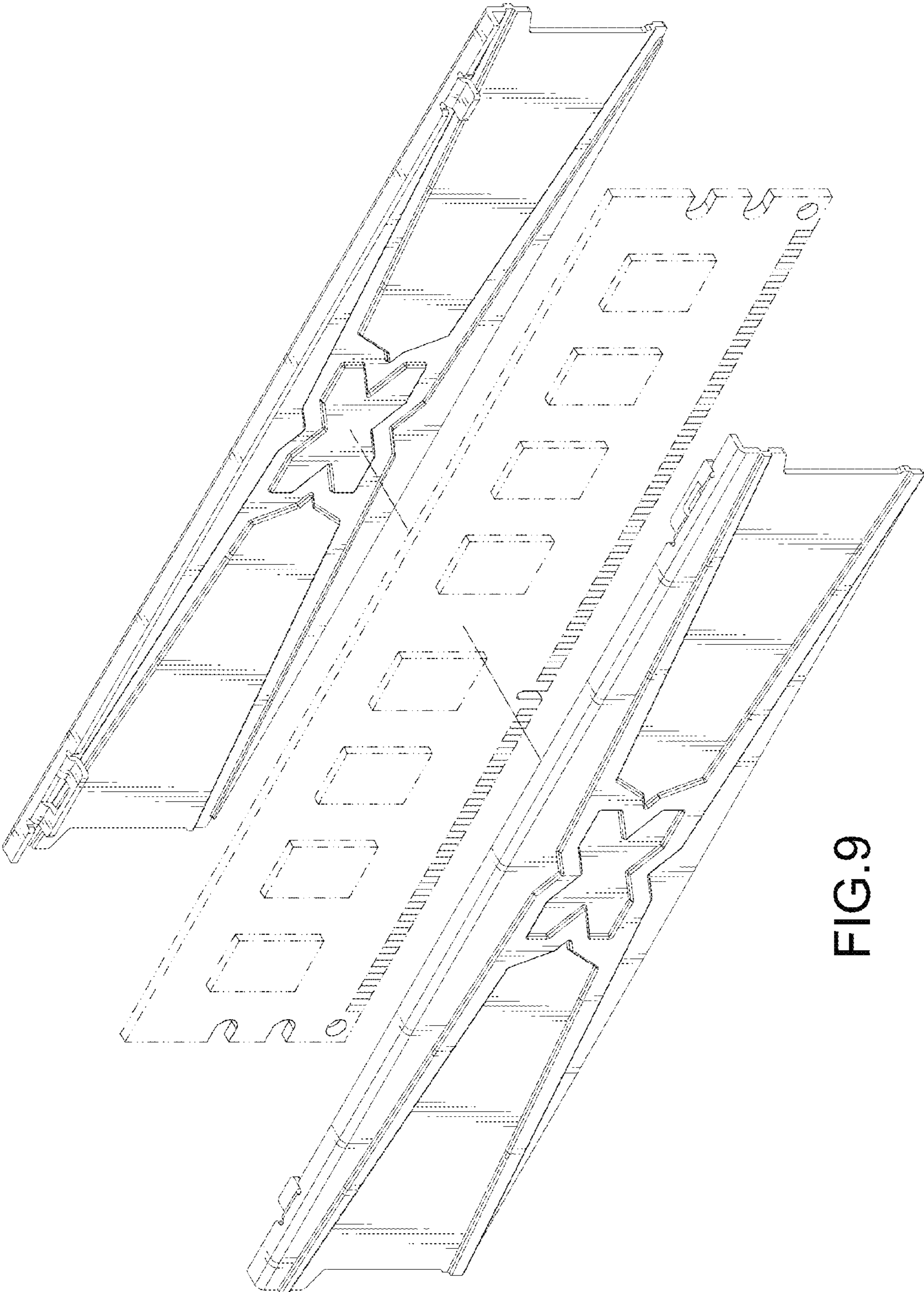


FIG.9